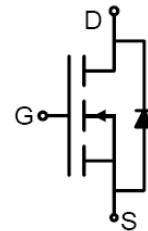
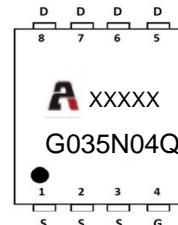


Feature

- 40V,70A
- $R_{DS(ON)} < 3.5 \text{ m}\Omega$ @ $V_{GS}=10\text{V}$ (TYP: $2.8 \text{ m}\Omega$)
- $R_{DS(ON)} < 5.2 \text{ m}\Omega$ @ $V_{GS}=4.5\text{V}$ (TYP: $4.4 \text{ m}\Omega$)
- Split Gate Trench Technology
- Lead free product is acquired
- Excellent $R_{DS(ON)}$ and Low Gate Charge



Schematic Diagram



Marking and pin Assignment

Application

- PWM applications
- Load Switch
- Power management

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity (PCS) |
|----------------|------------|----------------|-----------|------------|----------------|
| G035N04Q | APG035N04Q | PDFN3X3 | 13 inch | - | 5000 |

ABSOLUTE MAXIMUM RATINGS ($T_J=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|--|-----------|----------|---------------------------|
| Drain-Source Voltage | V_{DS} | 40 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current ($T_a = 25^\circ\text{C}$) | I_D | 70 | A |
| Continuous Drain Current ($T_a = 100^\circ\text{C}$) | I_D | 51 | A |
| Pulsed Drain Current ⁽¹⁾ | I_{DM} | 280 | A |
| Single Pulsed Avalanche Energy ⁽²⁾ | E_{AS} | 76 | mJ |
| Power Dissipation | P_D | 40 | W |
| Thermal Resistance from Junction to Case | R_{eJC} | 3.1 | $^\circ\text{C}/\text{W}$ |
| Junction Temperature | T_J | 150 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | -55~+150 | $^\circ\text{C}$ |

MOSFET ELECTRICAL CHARACTERISTICS($T_J=25^\circ\text{C}$ unless otherwise noted)

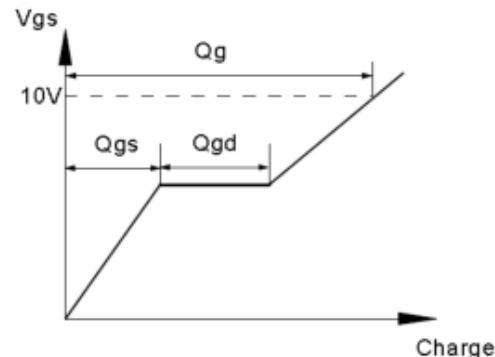
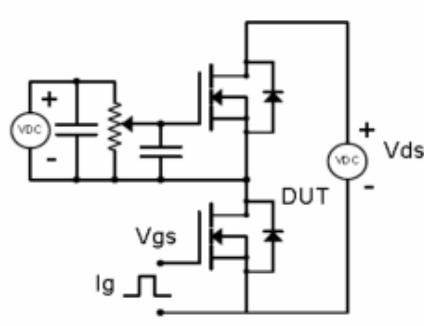
| Parameter | Symbol | Test Condition | Min | Type | Max | Unit |
|---|-----------------------------|---|-----|------|-----------|------------------|
| Static Characteristics | | | | | | |
| Drain-source breakdown voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$ | 40 | - | - | V |
| Zero gate voltage drain current | I_{DSS} | $V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}$ | - | - | 1 | μA |
| Gate-body leakage current | I_{GSS} | $V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$ | - | - | ± 100 | nA |
| Gate threshold voltage ⁽³⁾ | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$ | 1.2 | 1.7 | 2.2 | V |
| Drain-source on-resistance ⁽³⁾ | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$ | - | 2.8 | 3.5 | $\text{m}\Omega$ |
| | | $V_{\text{GS}} = 4.5\text{V}, I_D = 15\text{A}$ | - | 4.4 | 5.2 | |
| Gate Resistance | R_g | $V_{\text{DS}} = V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$ | - | 8.4 | - | Ω |
| Dynamic characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$ | - | 1280 | - | pF |
| Output Capacitance | C_{oss} | | - | 426 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 30 | - | |
| Switching characteristics | | | | | | |
| Turn-on delay time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}} = 20\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_G = 6\Omega$ | - | 7 | - | ns |
| Turn-on rise time | t_r | | - | 6.5 | - | |
| Turn-off delay time | $t_{\text{d}(\text{off})}$ | | - | 29 | - | |
| Turn-off fall time | t_f | | - | 13 | - | |
| Total Gate Charge | Q_g | $V_{\text{DS}} = 20\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$ | - | 20.3 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 3.9 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 4.2 | - | |
| Reverse Recovery Charge | Q_{rr} | $I_F = 15\text{A}, di/dt = 100\text{A}/\text{us}$ | | 17 | | nC |
| Reverse Recovery Time | T_{rr} | $I_F = 15\text{A}, di/dt = 100\text{A}/\text{us}$ | | 30 | | ns |
| Source-Drain Diode characteristics | | | | | | |
| Diode Forward voltage ⁽³⁾ | V_{SD} | $V_{\text{GS}} = 0\text{V}, I_S = 50\text{A}$ | - | - | 1.2 | V |
| Diode Forward current ⁽⁴⁾ | I_S | | - | - | 70 | A |

Notes:

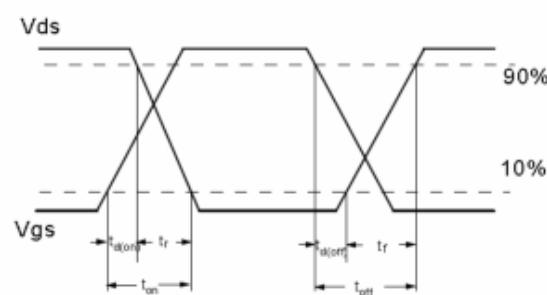
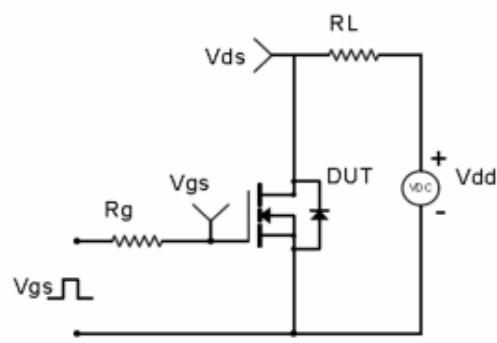
1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: $T_J=25^\circ\text{C}, V_{\text{DD}}=20\text{V}, R_G=50\Omega, L=0.5\text{Mh}, I_{\text{AS}}=17.5\text{A}$
3. Pulse Test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
4. Surface Mounted on FR4 Board, $t \leq 10$ sec

Test Circuit & Waveform

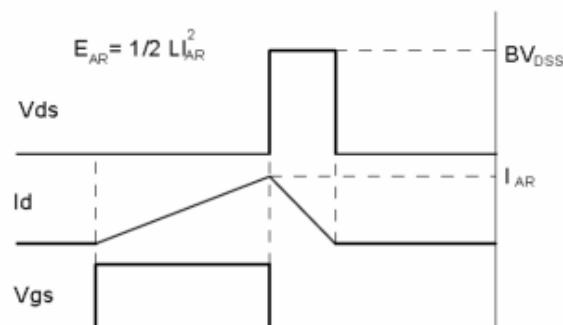
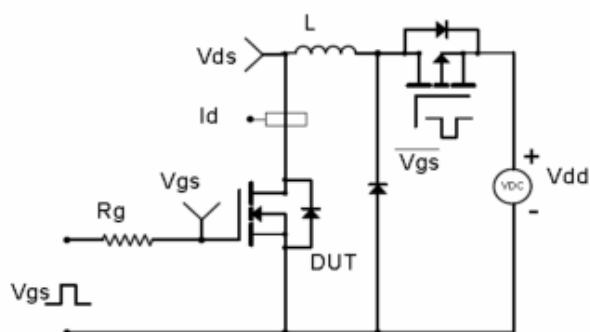
Gate Charge Test Circuit & Waveform



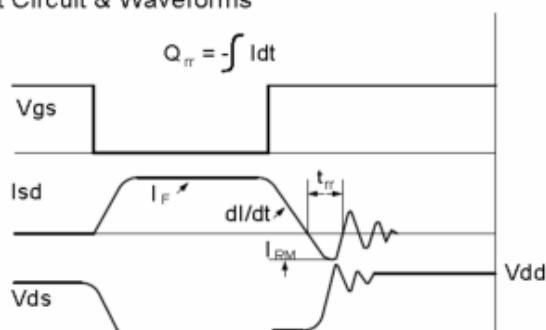
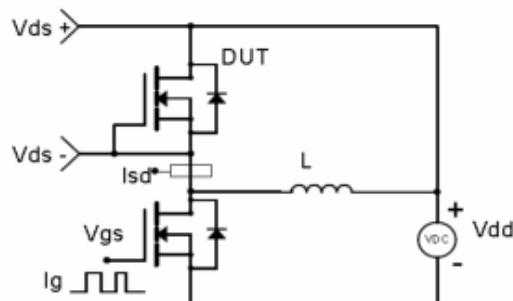
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Electrical Characteristics Diagrams

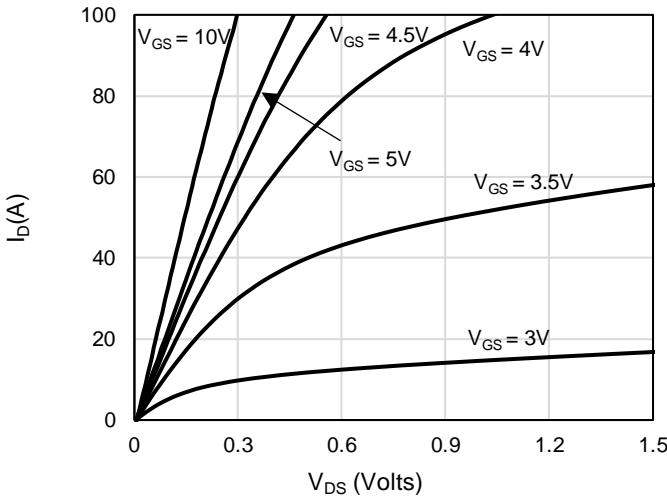


Figure 1: On-Region Characteristics

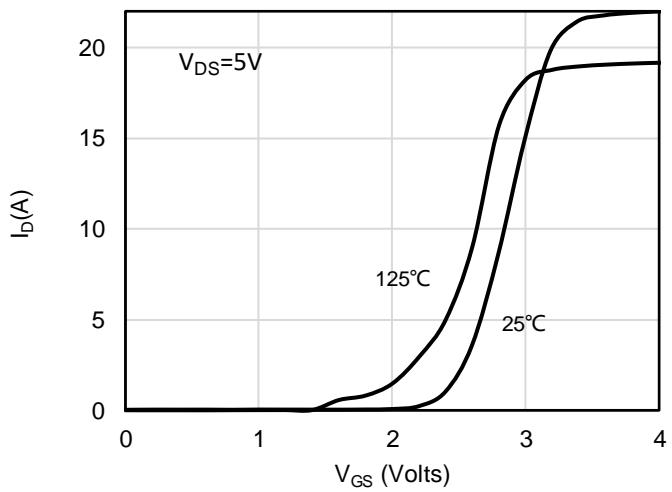


Figure 2: Transfer Characteristics

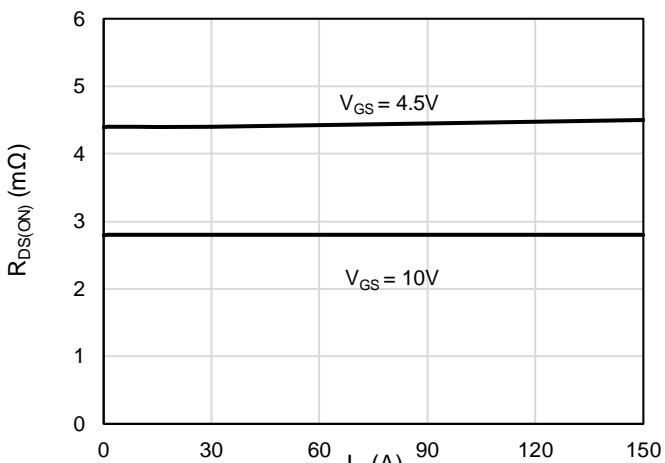


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

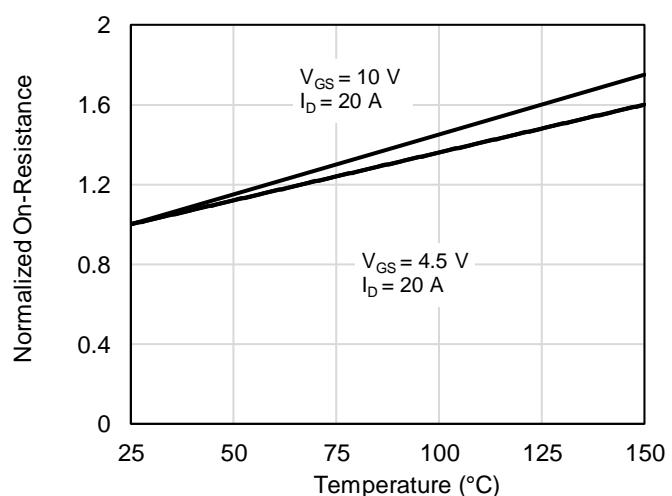


Figure 4: On-Resistance vs. Junction Temperature

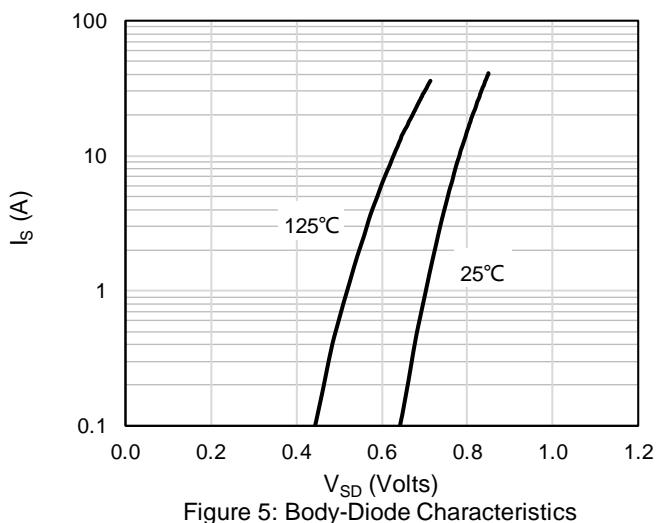


Figure 5: Body-Diode Characteristics

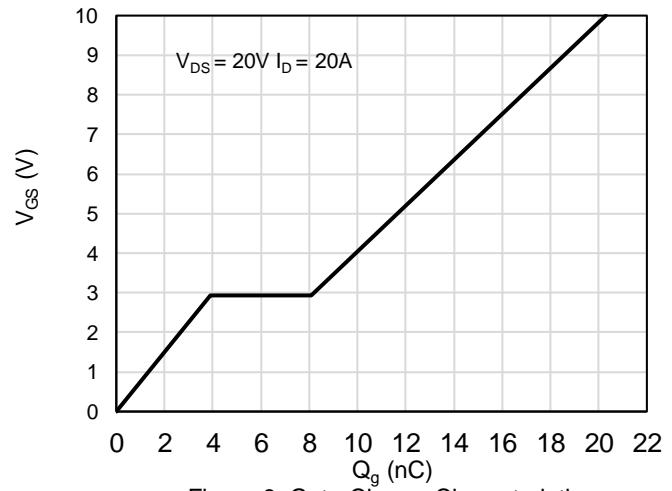


Figure 6: Gate-Charge Characteristics

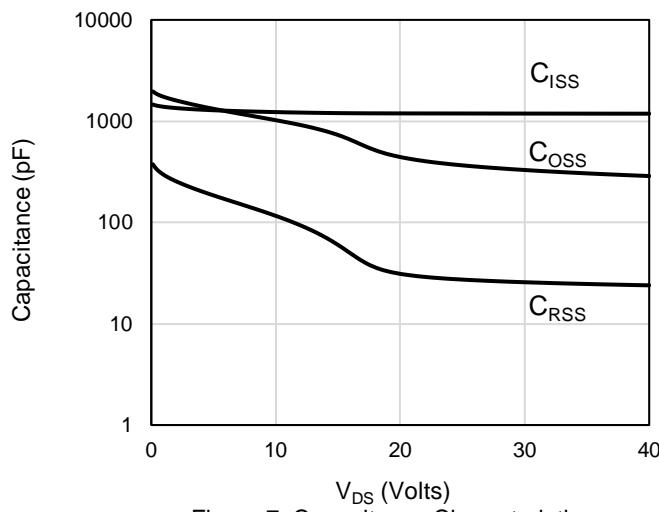


Figure 7: Capacitance Characteristics

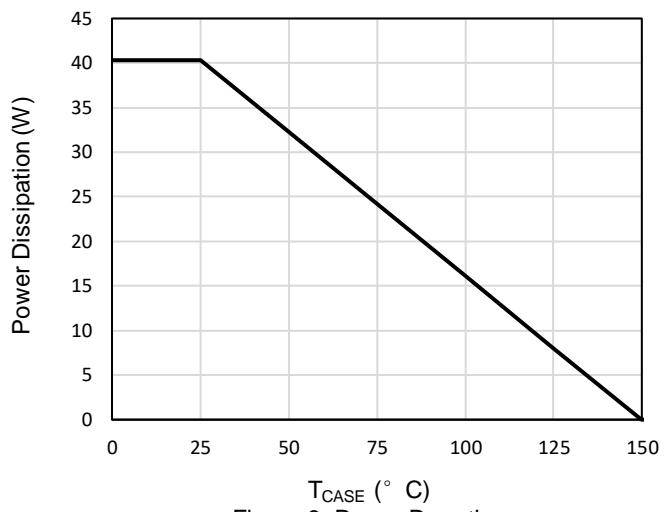


Figure 8: Power De-rating

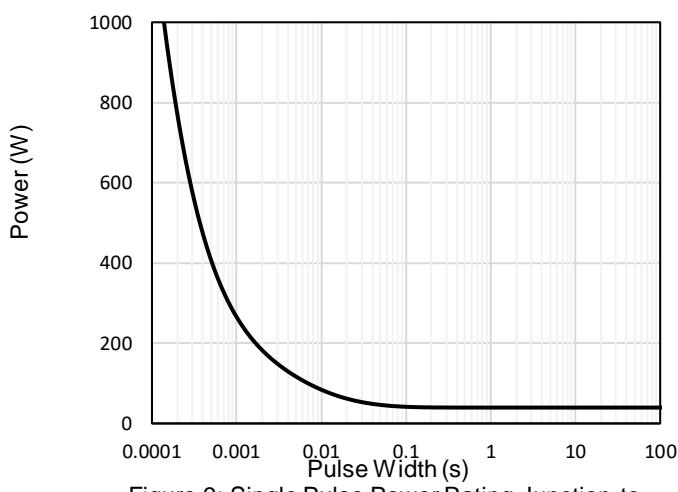


Figure 9: Single Pulse Power Rating Junction-to-Case

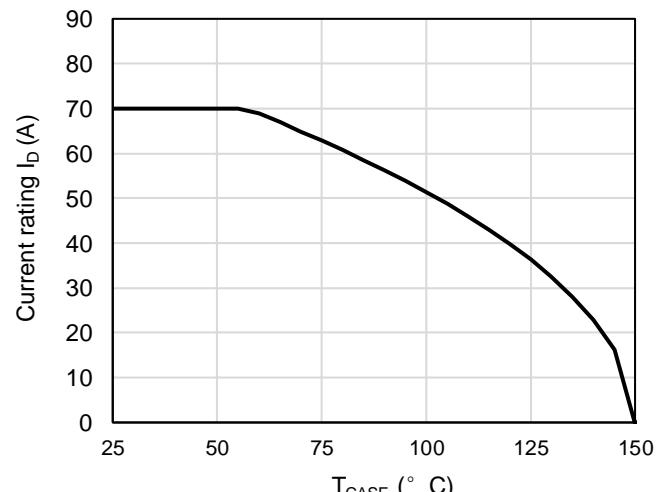


Figure 10: Current De-rating

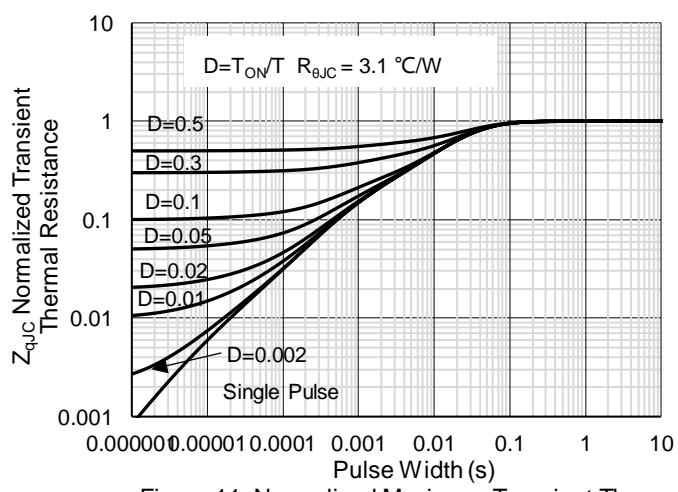


Figure 11: Normalized Maximum Transient Thermal Impedance

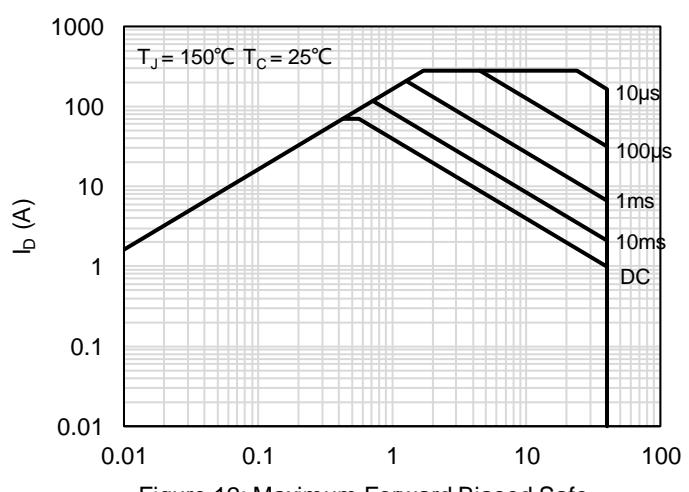
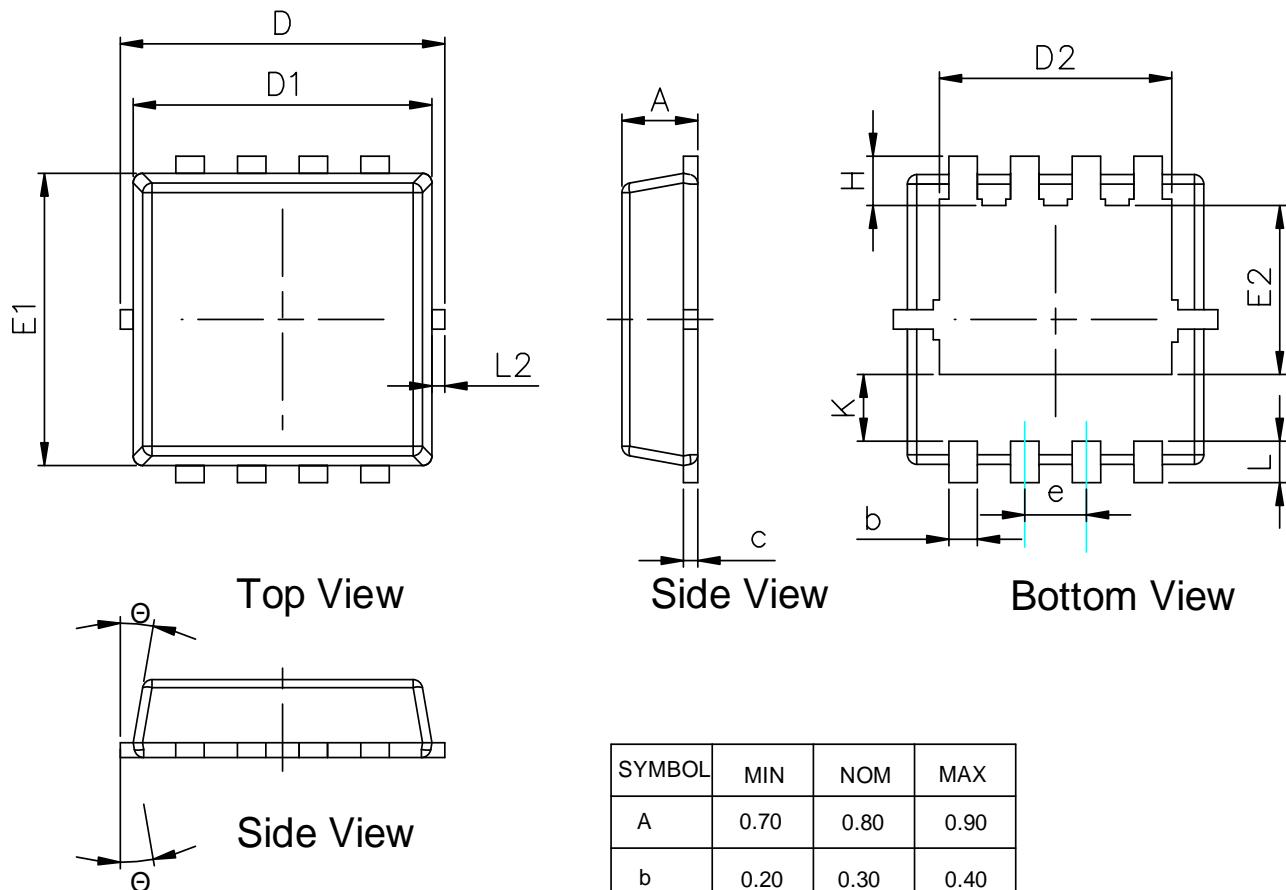


Figure 12: Maximum Forward Biased Safe Operating Area

Package Outlines



| SYMBOL | MIN | NOM | MAX |
|----------|----------|-------|-------|
| A | 0.70 | 0.80 | 0.90 |
| b | 0.20 | 0.30 | 0.40 |
| c | 0.14 | 0.15 | 0.25 |
| D | 3.20 | 3.30 | 3.40 |
| D1 | 3.00 | 3.15 | 3.30 |
| D2 | 2.35 | 2.45 | 2.55 |
| e | 0.65 BSC | | |
| E | 3.25 | 3.35 | 3.45 |
| E1 | 2.85 | 3.00 | 3.15 |
| E2 | 1.635 | 1.735 | 1.835 |
| H | 0.41 | 0.56 | 0.71 |
| K | 0.585 | 0.685 | 0.785 |
| L | 0.30 | 0.40 | 0.50 |
| L1 | 0.05 | 0.15 | 0.25 |
| L2 | — | — | 0.15 |
| Θ | 8° | 10° | 12° |

COMMON DIMENSIONS
(UNITS OF MEASURE = MILLIMETER)